

Materials Declaration

Package	PDIP
Body Size	300 mils
LeadCount	14
Option	PbFree

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Cresol Novolac	16	1.02 E-01	104198
SiO2 Filler	72	4.57 E-01	468893
Phenol Novolac	8	5.08 E-02	52099
Antimony_Sb2O3	2.2	1.40 E-02	14327
Brominated Resin	1.6	1.02 E-02	10420
Carbon Black	0.2	1.27 E-03	1302

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	3.06 E-01	313668
Fe	2.35	7.37 E-03	7560
P	0.03	9.41 E-05	97
Zn	0.12	3.76 E-04	386

Die Attach Paste

Item	PPM	Method
Pb	<2	ICP AES
Cd	<2	ICP AES
Hg	<2	ICP AES
Cr+6	<2	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	9.21 E-04	945

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.54 E-02	15831

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.72 E-04	176

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	9.08 E-03	9310

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.92 E-04	197
Ag Filler	75	5.75 E-04	590

Package Totals

Weight (g)	PPM
9.75 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

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LeadCount	14
Option	Sn/Pb

Molding Compound

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Epoxy Cresol Novolac	16	1.02 E-01	104198
SiO2 Filler	72	4.57 E-01	468893
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Antimony_Sb2O3	2.2	1.40 E-02	14327
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Carbon Black	0.2	1.27 E-03	1302

Molding Compound

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Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	3.06 E-01	313668
Fe	2.35	7.37 E-03	7560
P	0.03	9.41 E-05	97
Zn	0.12	3.76 E-04	386

Die Attach Paste

Item	PPM	Method
Pb	<2	ICP AES
Cd	<2	ICP AES
Hg	<2	ICP AES
Cr+6	<2	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	9.21 E-04	945

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.31 E-02	13456
Pb	15	2.32 E-03	2375

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.72 E-04	176

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	9.08 E-03	9310

Die Attach

Item	% of Die Attach	Weight (g)	PPM
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